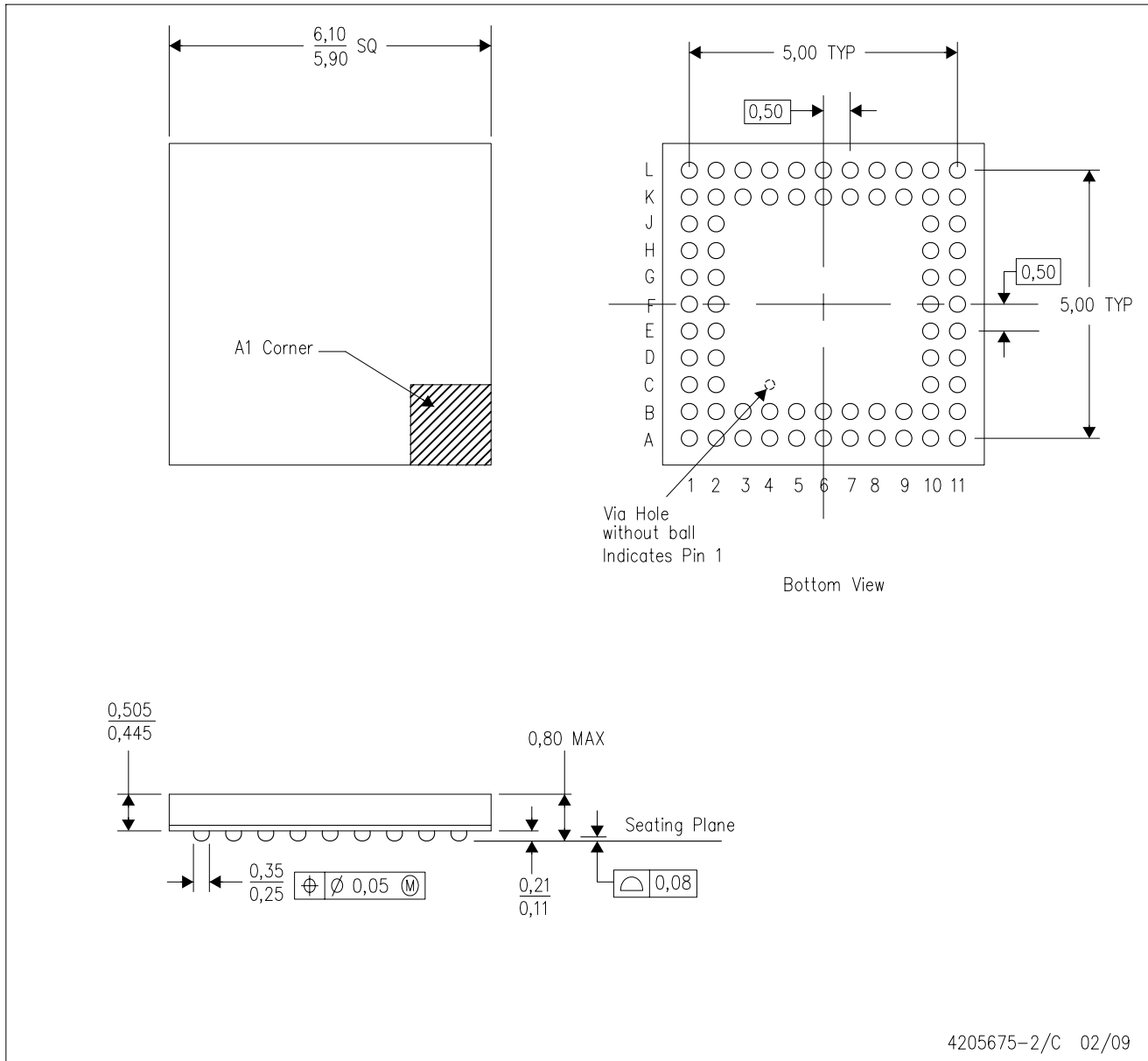


ZSP (S-PBGA-N72)

PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. MicroStar Junior™ BGA configuration
 - D. Falls within JEDEC MO-225
 - E. This is a Pb-free solder ball design.

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